

工學碩士 學位論文

Al

**A Study on the Solid Diffusion Bonding of
Al Alloy/STS Steel**

指導教授 金 永 植

2000年 2月

韓國海洋大學校 大學院

材 料 工 學 科

李 京 植

本 論 文 李 京 植 工 學 碩 士 學 位 論 文 認 准

主 審 : 工 學 博 士 李 成 烈 ()

委 員 : 工 學 博 士 金 允 海 ()

委 員 : 工 學 博 士 金 永 植 ()

2000年 2月

韓 國 海 洋 大 學 校 大 學 院

材 料 工 學 科

李 京 植

Abstract

1.	1
1.1	1
1.2	2
1.3	6
1.4	10
2.	12
2.1	12
2.2	14
2.2.1	14
2.2.2	14
2.2.3	15
3.	17
3.1 , creep 가	17
3.2	21
3.3	27
3.4	29
3.5	30
3.6 EDX XRD	

	40
3.7	44
4.	46
	47

A Study on the Solid Diffusion Bonding of Al Alloy/STS Steel

Kyoung-Sik Lee

Department of Materials Engineering

Graduate School

Korea Maritime University

Abstract

Microstructural analysis and tensile testing of directly diffusion-bonded joints of A6061(T6) to STS316L were conducted in order to evaluate the joinability of aluminum alloy to stainless steel. Diffusion bonding of A6061(T6)/ STS316L was carried out at 748–883K for 30min–150min applying 1–8 MPa in vacuum degree of 10^{-5} Torr.

SEM observation revealed that the reaction layer was formed at the A6061(T6)/STS316L interface. It was referred that the intermetallic compounds such as $FeAl_3$, Fe_2Al_5 were identified in the reaction layer in the different literature. However, various intermetallic compounds which is not same as $FeAl_3$, Fe_2Al_5 were founded in this experiment. It was explained that the reaction layer was formed by reciprocal action of reaction and diffusion. The tensile strength of A6061(T6)/STS316L joints was risen up to about 140 MPa. The fracture modes shifted from the ductile fracture to the brittle fracture in reaction

layer with increasing of the temperature.

XRD analysis revealed that the fracture surface contains a large amount of Al elements in the temperature of 748–803K. It was identified that the fracture occurred at the A6061 side at this temperature. However, it was identified that the fracture occurred at the intermetallic compounds in the temperature above 813K.

Main conclusions are obtained as follows;

1. The most suitable bonding conditions which the tensile strength of the joints was risen up to 140 MPa were clarified to be the bonding temperature of 748–803K, the time of 90–150min, the pressure of 1–3 MPa and vacuum degree of 10^{-5} Torr.
2. In the temperature of 748–803K, tensile strength of the joints was increased by reciprocal action of reaction and diffusion with increasing of the temperature. However, in the temperature above 813K, tensile strength of the joints was decreased by excessive formation of brittle intermetallic compounds and by transmitting cracking due to thermal stress.
3. In the temperature of 748–803K, fracture occurred at the A6061 side in ductile fracture modes. However, in the temperature above 813K, fracture occurred at the interface in brittle fracture modes.
4. In the temperature of 748–803K, it seems that Fe, Cr, Ni and other elements of STS 316L side diffuses into A6061 side, therefore the tensile strength is risen by forming thin and

strongly combined reaction layer. However, in the temperature above 813K, it seems that the above elements diffuses excessively into A6061 side, therefore the tensile strength falls down by forming thick and brittle reaction layer and by inducing stress concentration at the intermetallic compounds inside of reaction layer in the interface.

가 .

, 同種

, Insert metal

Fig. 1(b)

, Insert metal

, 異種

ceramics

(TLP)

Insert metal

,

Insert metal

,

5)

Fig. 1(c)

Ni

1.2

(

,

)

2), 4), 5)

,

1)

()

,

,

,

2) 同種

,

,

3)

,

(Zr, Ti),

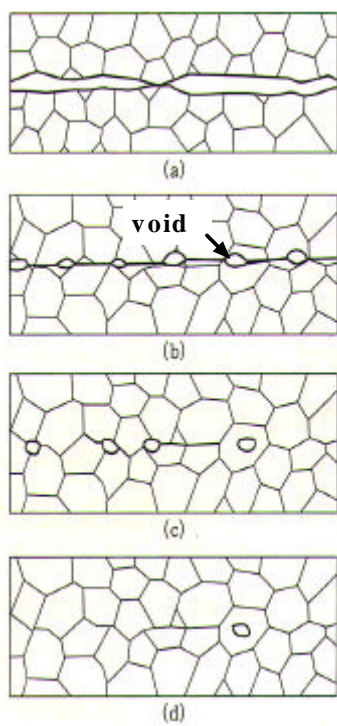
,

4)

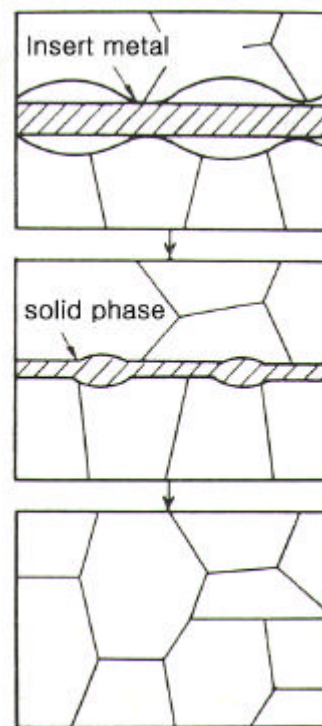
가

.

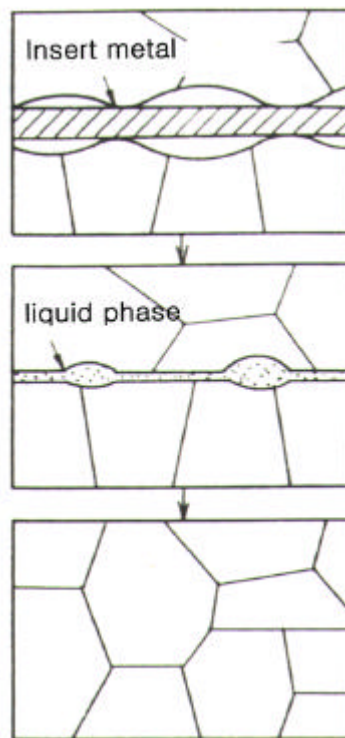
- 5) 가 ,
가 .
- 6) , .
- 7) .
- 8) 가 .
- 9) 異種 () 異種
 , - .
- 10) 가 가 .
- 11) 異種 Insert metal
 , II 13).
 , 가 가 .
- 1) .
- 2) 가 가
- 3) 가 ,
가 가 .
- 4) .



(a) Solid phase diffusion bonding(no Insert metal)



(b) Solid phase diffusion bonding(used Insert metal)



(c) TLP diffusion bonding

Fig. 1 A theory of diffusion bonding

1.3

가 異種 , 異種

異種 ,

가 ,

5), 14).

A6061 (Al- Mg- Si)

STS316L

Mg 6)

Table 1, 2 7) 9).

(1/2 2/3T_m T_m :)

가

가

가

, 2

가

가 . , 가

가 가

10-3 10-5 Torr . , Al
10-5 Torr

가 2, 5, 6.

, 2, 14). Hot Press(가)
HIP(가) ,

1) Hot Press

- a. 가 .
 - b. . ,
 - c. 가 .
 - d. 가 ,
- . , 가 ,

2) HIP

- a. , , , ,
- b. .
- c. 가 가
가 .

Hot Press

HIP

異種材

異種材

()

(intermetallic compounds)

5).

異種材

void가

가

Table 1 Chemical compositions of materials used(wt %)

	Fe	Al	Cr	Ni	Mg	Si	Mn
STS316L	bal.	-	16.0 18.0	12.0 15.0	-	1.0	2.0
A6061	0.03	bal.	0.04 0.35	-	0.8 1.2	0.4 0.8	0.15

	C	Mo	P	Cu	S	Zn	Ti
STS316L	0.03	2.0 3.0	0.04	-	0.03	-	-
A6061	-	-	-	0.15 0.4	-	0.25	0.15

Table 2 Physical and mechanical properties of materials used

	m.p (K)	thermal expansion coeff. (1/) $\times 10^{-6}$	thermal conductivity (100) (cal/cm ² · sec)	modulus of elasticity (MPa)	tensile strength (MPa)	load at 0.2% elongation (MPa)	elongation (%)
A6061	853 923	24	0.37	68.6	310	275	12
STS316L	1643 1673	16	0.05	19.3 × 10 ⁴	558	290	50

1.4

가

가

10), 15).

가

異種

가

가

가

A6061(T6)

가

가

3), 8), 10), .

가

가

16) 18).

,

,

,

,

가

.

,

, 異種

Insert metal

,

가

.

, Ag

Insert metal

,

,

1) 13)

.

,

cost

, Insert metal

,

.

,

A6061(T6)

STS316L

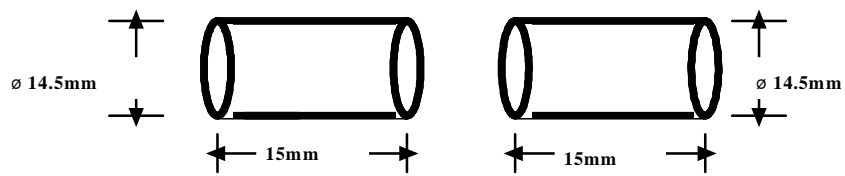
,

.

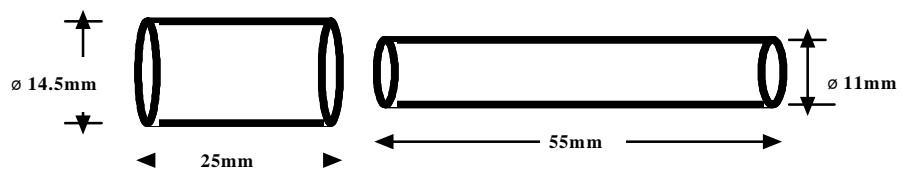
2.

2.1

A6061(T6) STS 316L
가 .
(\varnothing 14.5mm \times 15mm) 가 (A6061 \varnothing
14.5mm \times 25mm, STS 316L \varnothing 11mm \times 55mm) .
Fig. 2 .
A6061 가 , creep
, STS316L ,
가
. .
A6061 emery paper 1500A $3\mu\text{m}$ 1
 μm , STS 316L (Anchoring) , emery
paper 1500Cw $3\mu\text{m}$ $1\mu\text{m}$, 1500Cw wire brush
, 10min
,



(a) Bonding specimen made for observation of reaction layer



(b) Bonding specimen made for tensile test

Fig. 2 Shape of specimen

2.2

Vacuum Hot Press Photo 1

, Fig. 2

2.2.1

748 883K, 30min 150min
, 가 0 8MPa 10-5
Torr

, Fig. 3 Jig 가 Press
alinement , Jig center가
, 가 Press 가 .
1 가 가 .

2.2.2

fine cutter
mounting , polishing , keller (2M \emptyset +
5M \emptyset + 3M \emptyset + 190M \emptyset) etching ,
(OM) (SEM)

, Instron type

가 , test

9mm

가

3.0 mm/min

test

2.2.3

SEM

EDX

XRD



Photo 1 Vacuum hot press

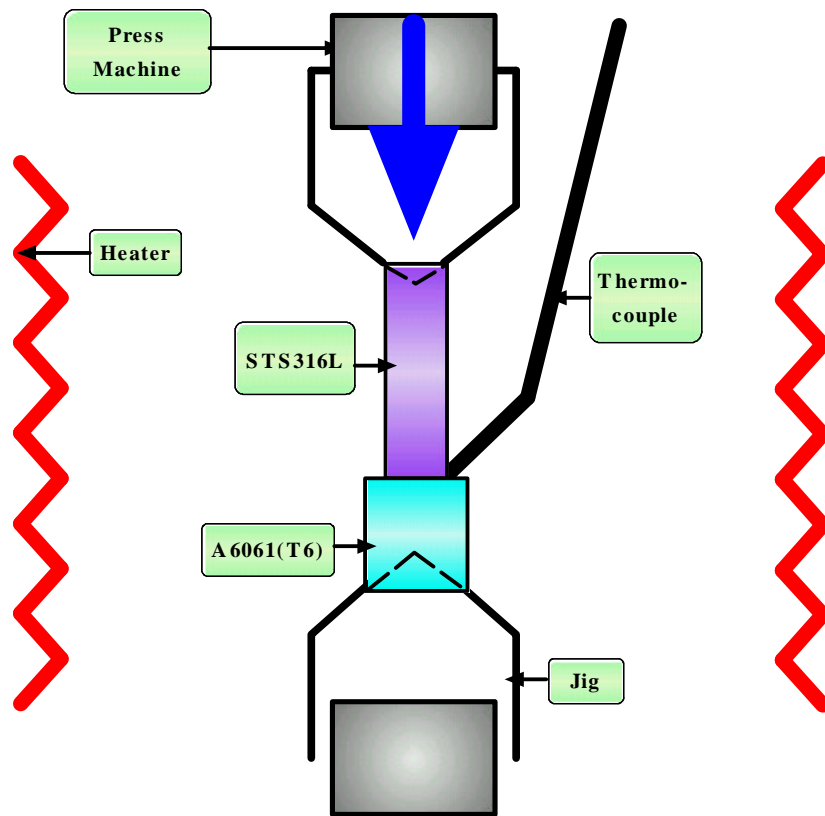


Fig. 3 Inside of vacuum hot press

3.

3.1 , creep 가

748K, 120min

, 가 1 8 MPa

가 . Fig. 4 Photo 2 (a), (b) .

가 가

. , 가 ,

, creep

.

1) . ,

alinement가

, 가 . , 가 5 8

MPa 가 , creep 가

. , Photo 3

가 1 3MPa 가

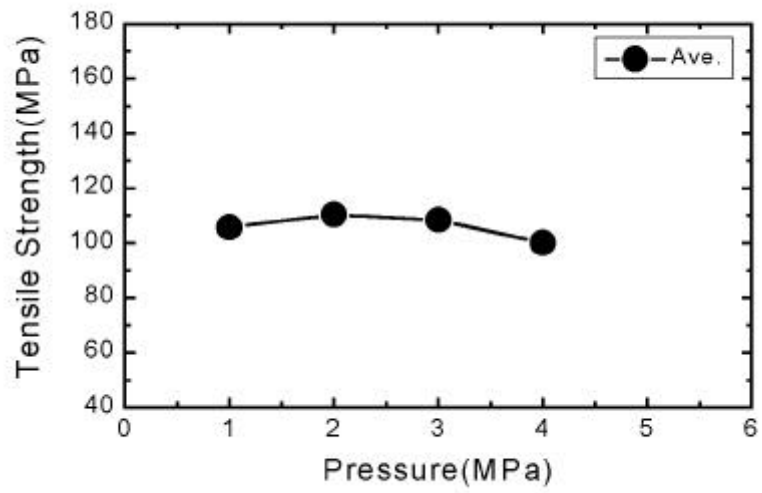
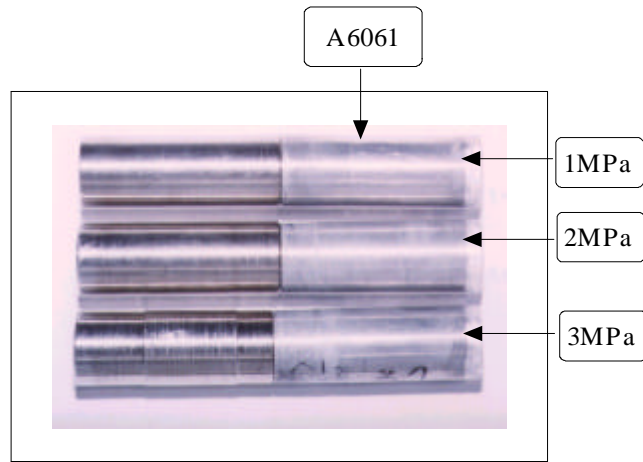
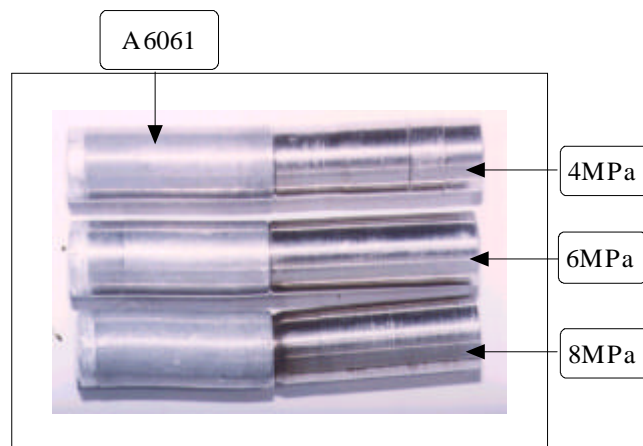


Fig. 4 Effect of pressure on tensile strength of A6061/STS316L joints (Bonding temp. : 748K, Bonding time : 120min)

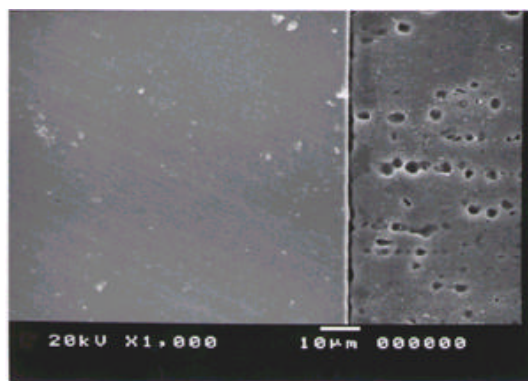


(a) at pressure of 1 3 MPa

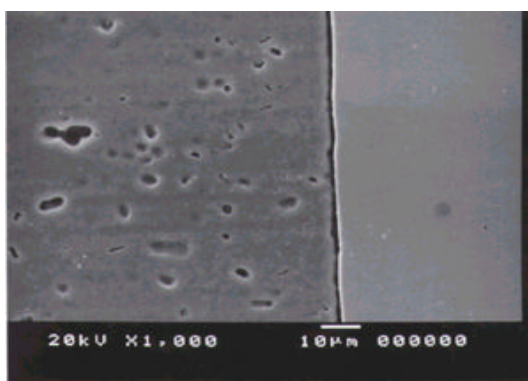


(b) at pressure of 4 8 MPa

Photo 2 Effect of pressure on creep of joints
(Bonding temp. : 748K, Bonding time : 120min)



(a) at pressure of 1.3MPa

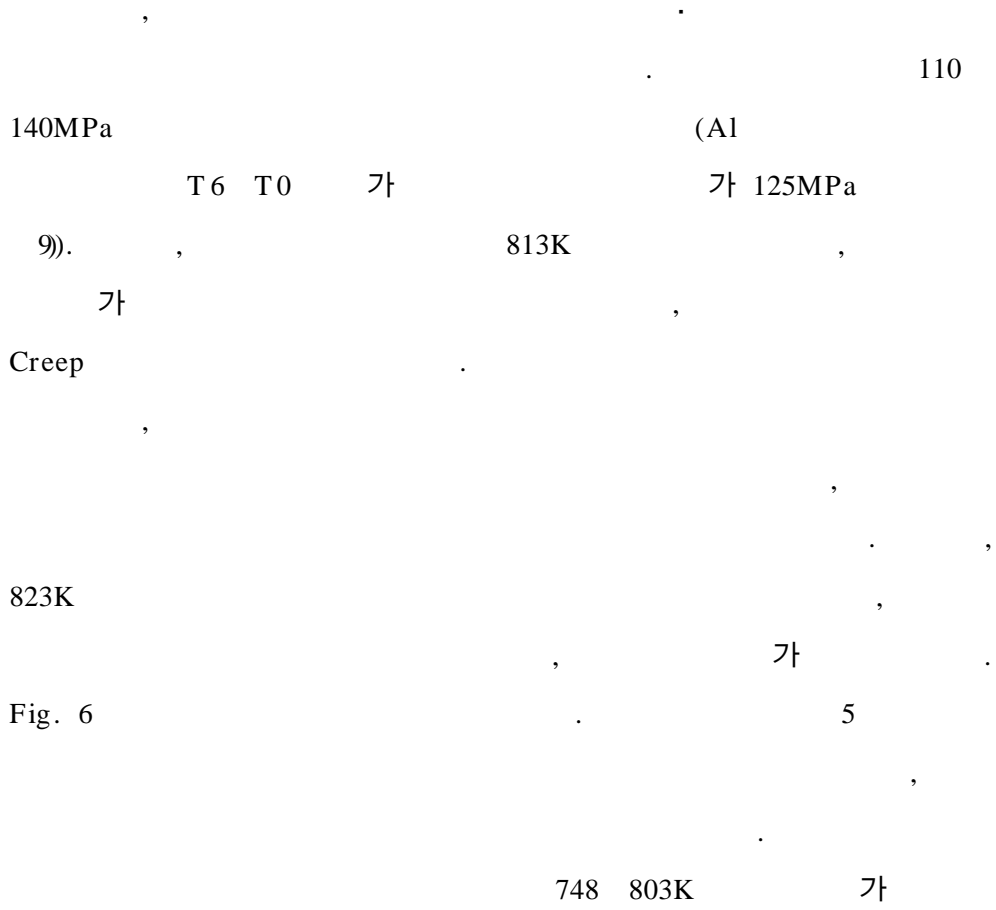


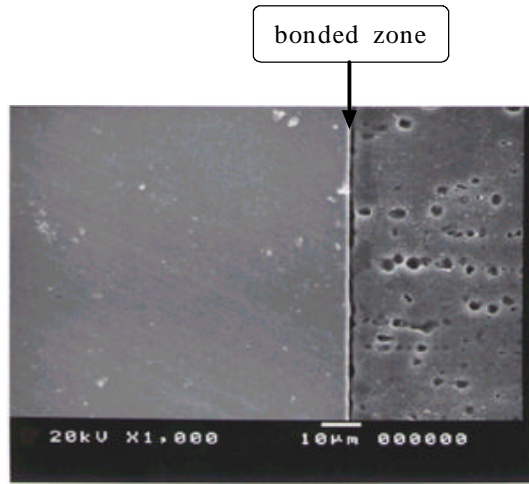
(b) at pressure of 8MPa

Photo 3 SEM microstructure of the A6061/STS316L joints
(Bonding temp. : 748K, Bonding time : 120min)

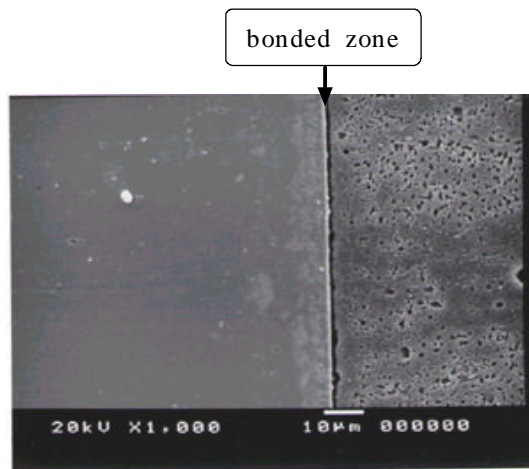
3.2

가 1
3MPa(creep 가
, 120min
SEM Photo 4, 5
, Fig. 5 line- scanning
, 748 798K
(1 μ m). , 823 883K
(10 30 μ m). ,
cutting ,
(intermetallic compounds)
Insert metal
, line- scanning
, A6061
가 가
test ,
가 803K 140MPa
가 가





(a) at 748K



(b) at 798K

Photo 4 SEM microstructure of the A6061/STS316L joints
[Bonding time : 120min, Pressure : 1 3MPa]

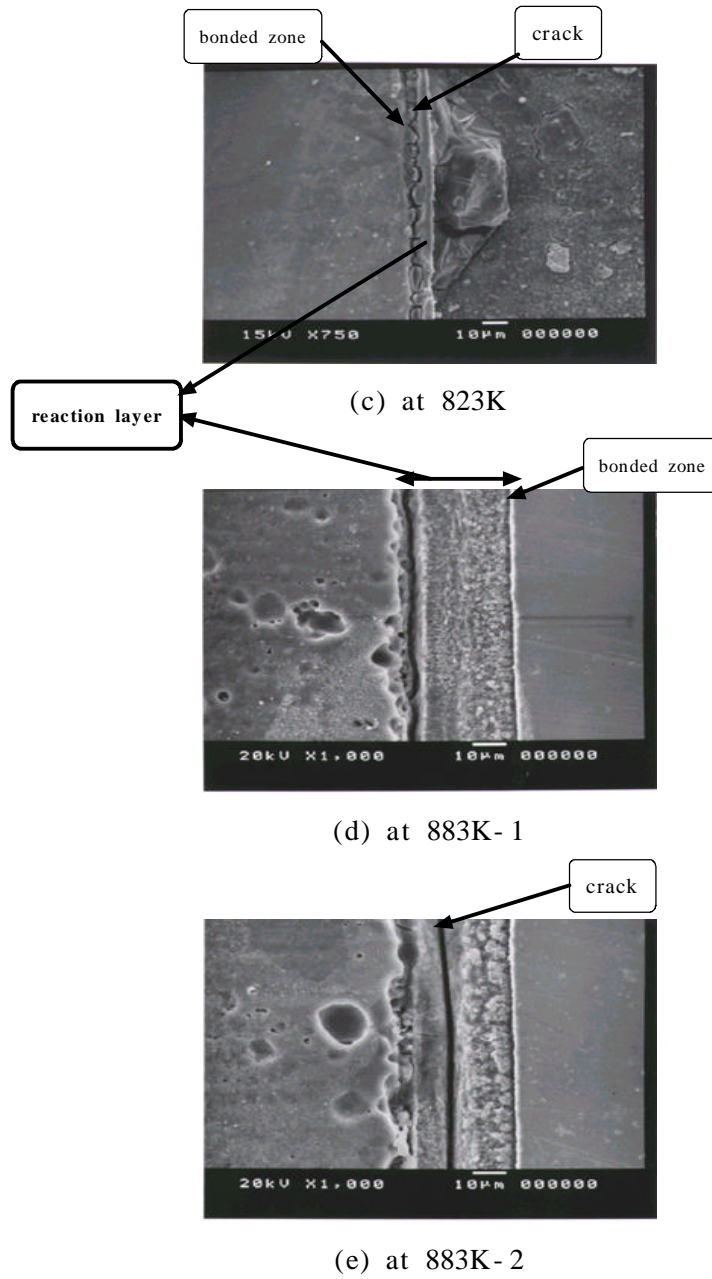
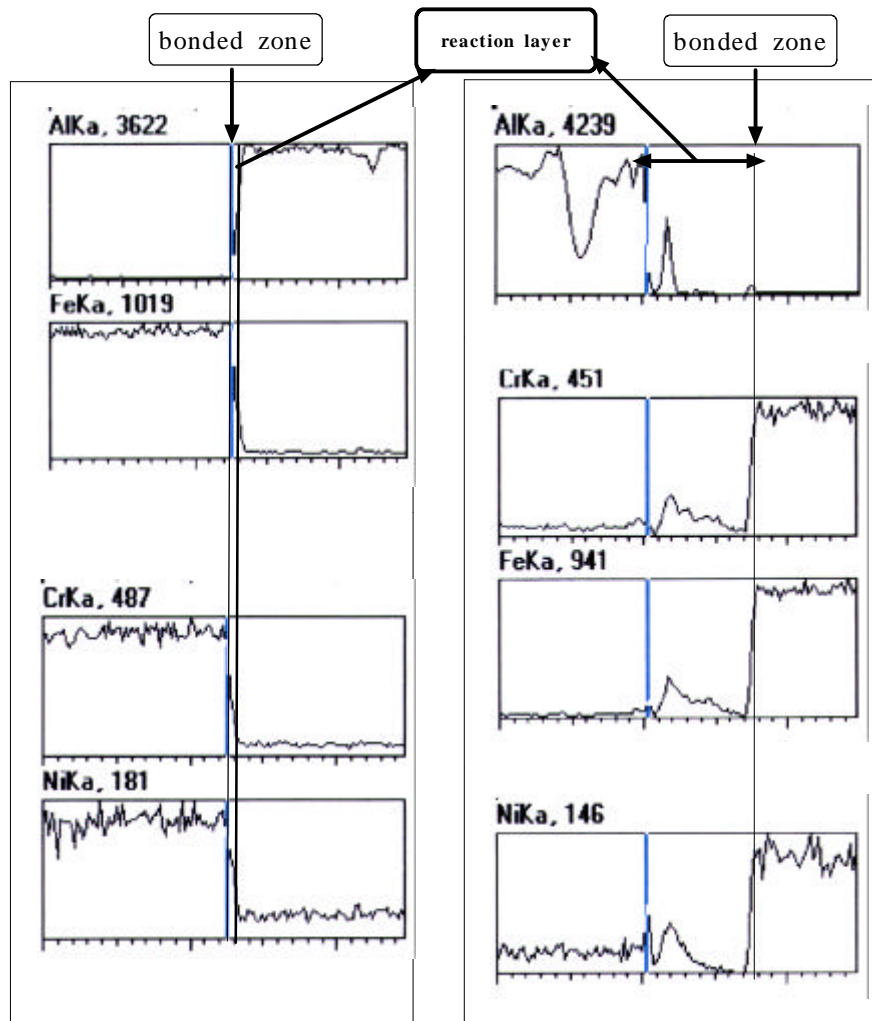


Photo 5 SEM microstructure of the A6061/STS316L joints
 [Bonding time : 120min, Pressure : 1 3MPa]



(a) at temp. of 748K

(a) at temp. of 883K

Fig. 5 Line-scanning of joints

(Bonding time : 120min, Pressure : 1 3MPa)

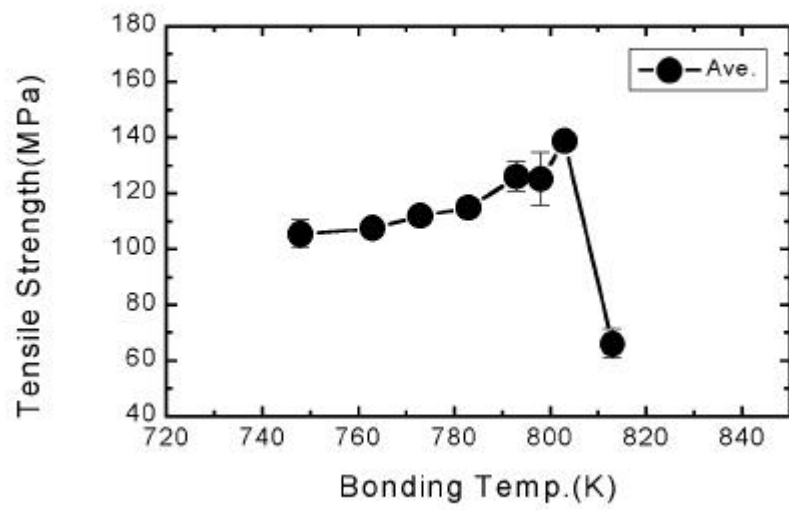


Fig. 6 Effect of bonding temp. on tensile strength of A6061/STS316L joints
[Bonding time : 120min, Pressure : 1 3MPa]

3.3

가 1 3MPa, 748K
, 30 150min
가

Fig. 7

가
가
가

90 150min

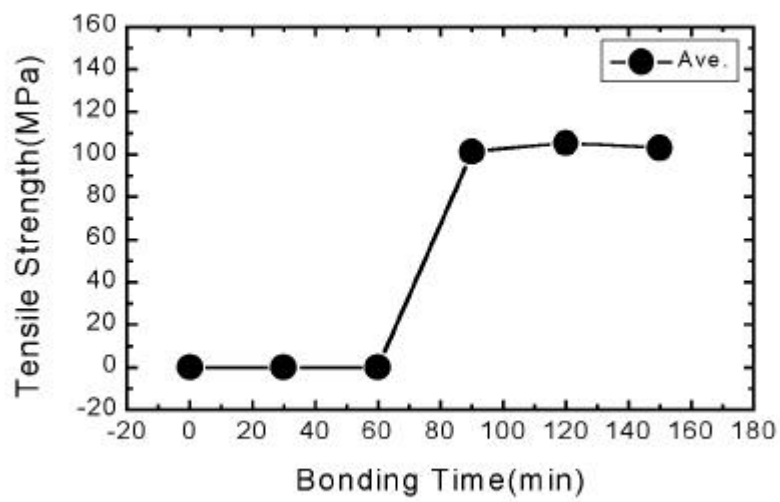


Fig. 7 **Effect of bonding time** on tensile strength of A6061/STS316L joints
[Bonding temp. : 748K, Pressure : 1 3MPa)

3.4

90 150min, 가 1 3MPa , 748 803K, 가

(1) A6061 STS316L 1 μ m Polishing

(2) A6061 1 μ m Polishing , STS 316L
wire brush

(Anchoring) 가

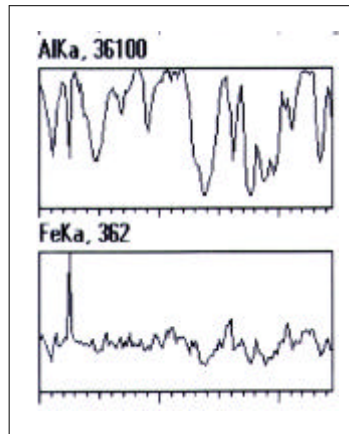
(2) 가 ,

3.5

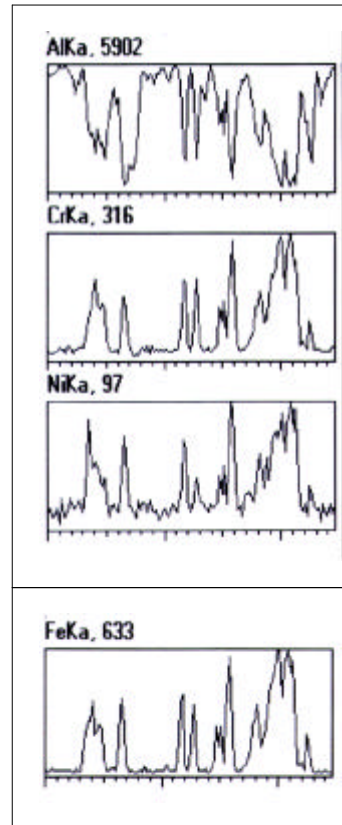
120min, 가 1 3MPa ,
748 823K . 가 748 803K
Photo 6 9 ,
dimple ,
A6061 . ,
813K 가
, A6061
Photo 10 .
, SEM Photo
11 13 . 가 , 74
8 803K A6061 dimple
, 813K ,
(
) . , dimple
가
, 748 803K , 가
. , A6061 가
dimple . ,
line- scanning , Al 가 .
Fig. 8 . , 813K

Al

가



(a) Al zone

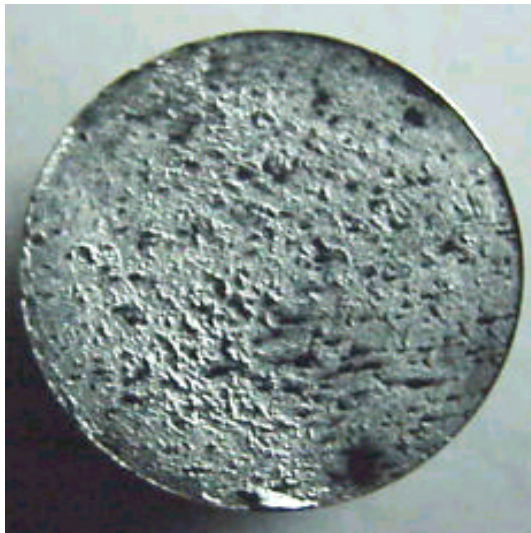


(b) STS zone

Fig. 8 Line-scanning of fracture surface
(Bonding temp. : 798K, Bonding time : 120min,
Bonding pressure : 1 3 MPa)



(a) Al side



(b) STS side

Photo 6 Shape of fracture surface at 748K



(a) Al side



(b) STS side

Photo 7 Shape of fracture surface at 783K



(a) Al side



(b) STS side

Photo 8 Shape of fracture surface at 798K



Photo 9 Shape of fracture at 748 803K

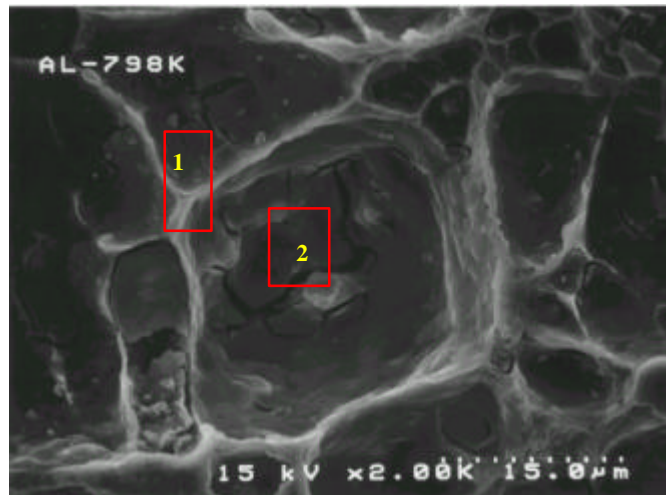


(a) Al side

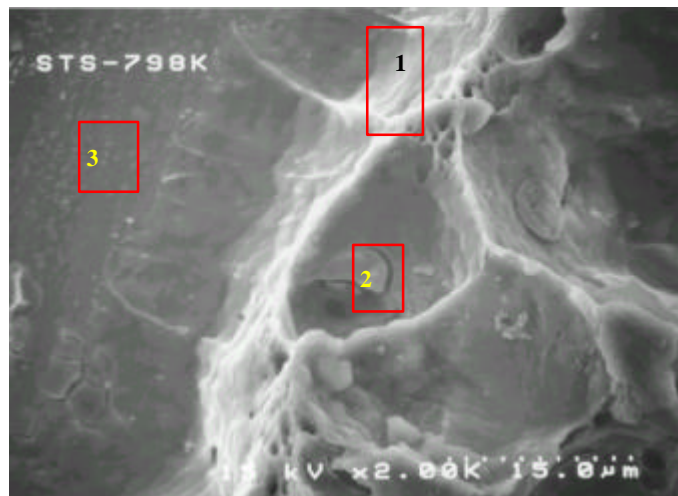


(b) STS side

Photo 10 Shape of fracture surface at 813K

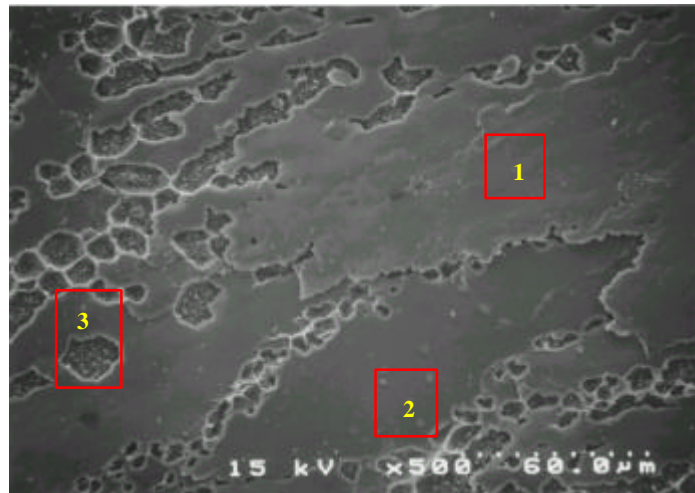


(a) Al zone

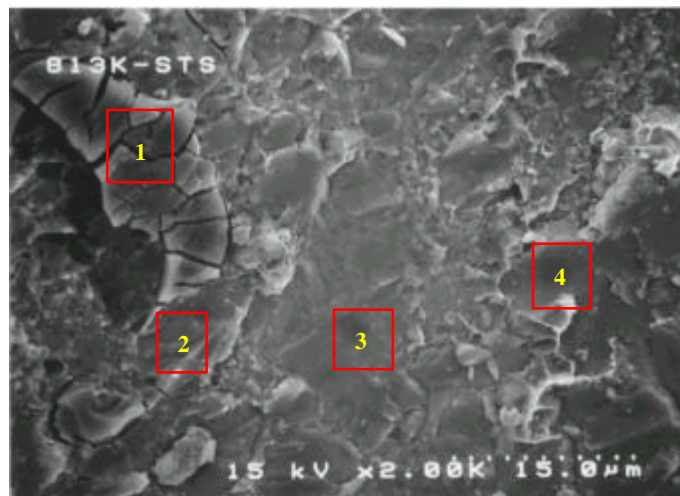


(b) STS zone

Photo 11 SEM microstructure of fracture surface
[798K, 1 3MPa, 120min]

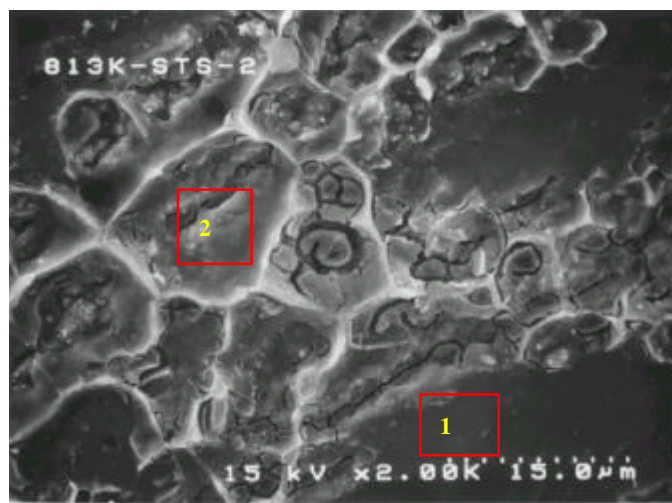


(a) Al zone



(b) STS side-1

Photo 12 SEM microstructure of fracture surface
[813K, 1 3MPa, 120min]



(c) STS side-2

Photo 13 SEM microstructure of fracture surface

[813K, 1 3MPa, 120min]

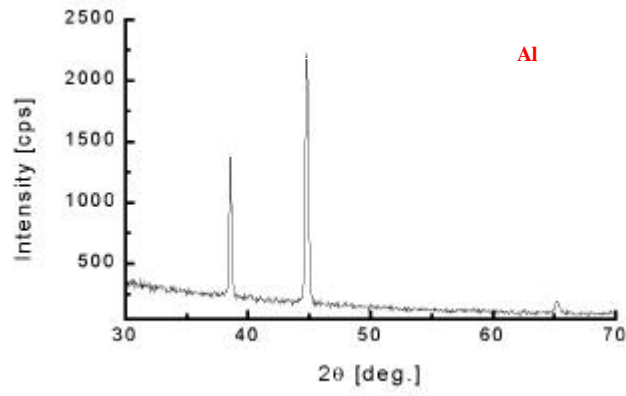
3.6

EDX XRD

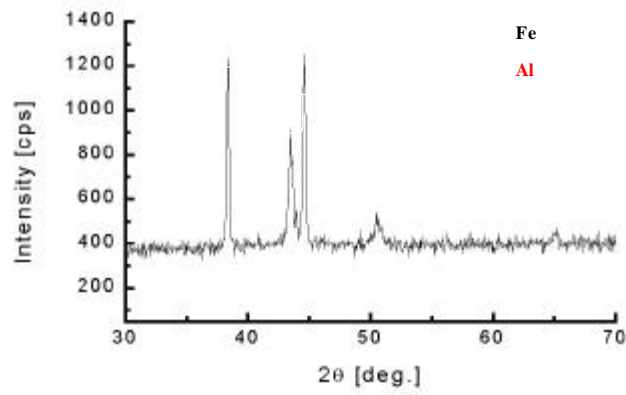
EDX ,
Photo 11 ,
dimple , 798K
EDX , Al ,
가 가 A6061
748 803K
Photo 12, 13
813K , Al ,
Fe, Cr, Ni ,
Al
() 가
X-ray
Fig. 9, 10 . 798K
Al Al , STS
Al Fe ,
Al
813K Al Al , STS Fe
Al Al
가 .

Table 3 EDX analysis of fracture surface

	798K					813K								
	Al		STS			Al			STS- 1				STS- 2	
Element \ No.	1	2	1	2	3	1	2	3	1	2	3	4	1	2
Al	100	97.52	100	100	32.75	67.11	97.33	100	60.81	68.12	34.01	71.55	70.64	78.7
Mg	-	-	-	-	-	-	2.67	-	-	-	-	-	-	-
Si	-	-	-	-	0.18	0.56	-	-	0.27	0.27	0.14	0.72	0.96	0.82
Fe	-	2.37	-	-	46.64	25.4	-	-	27.46	24.25	46.37	21.61	22.07	15.57
Cr	-	0.11	-	-	12.65	6.93	-	-	9.02	7.35	14.21	6.12	6.33	4.31
Ni	-	-	-	-	7.78	-	-	-	2.44	-	5.27	-	-	0.6
O	-	-	-	-	-	-	-	-	-	-	-	-	-	-
Total(wt%)	100													

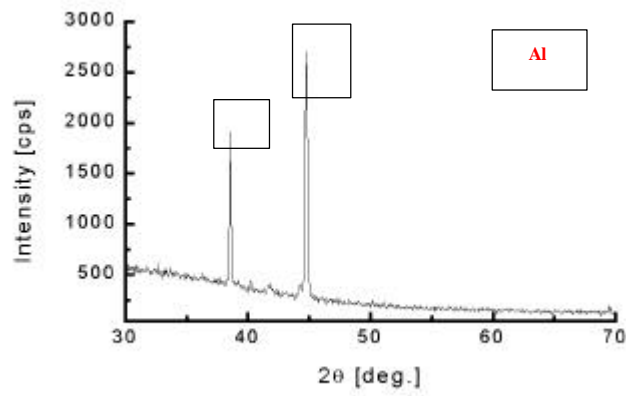


(a) Al side

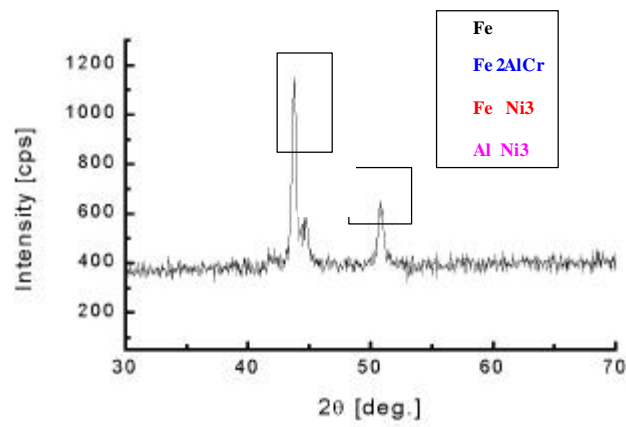


(b) STS side

Fig. 9 X-ray diffraction patterns from fracture surface
[Temp. : 798K, Time : 120min]



(a) Al side



(b) STS side

Fig. 10 X-ray diffraction patterns from fracture surface
 [Temp. : 813K, Time : 120min]

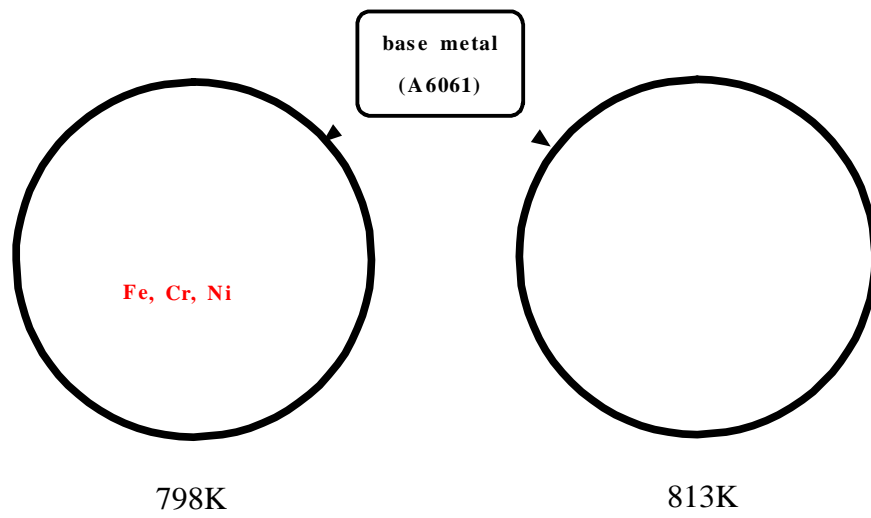


Fig. 11 A study of bonding mechanism 1

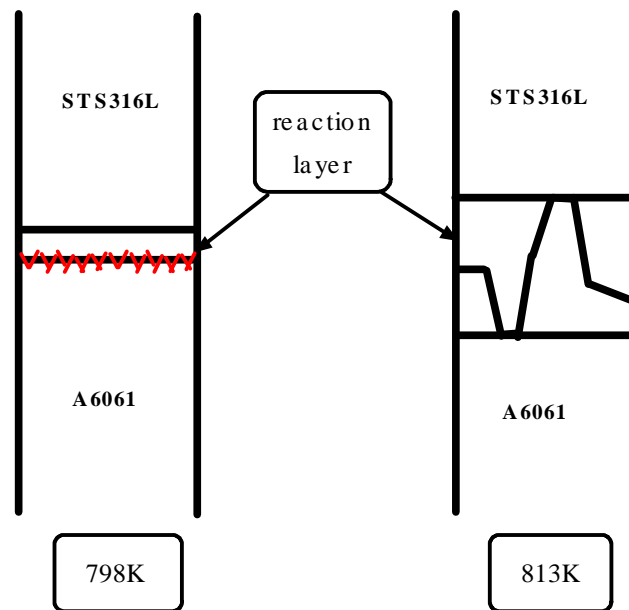


Fig. 12 A study of bonding mechanism 2

4.

A6061(T6) STS316L , ,
 , .

1. 748 803K, 90 150min, 가
1 3MPa, 10-5 Torr . ,
140MPa .

2. 748 803K , .
가 . , 813K ,
 .

3. 748 803K , Al 가
 . , 813K ,
 .

4. 748 803K ,
Fe, Cr, Ni Al ,
 . ,
813K 上記 가 ,
 ,
 .

- 1) 大橋 修, Q & A 擴散接合, 産報出版, pp. 22, pp. 30 31
- 2) 金永植, 最新熔接工學, 螢雪出版社, pp. 75 81
- 3) , , pp. 143 165, pp. 229 230,
pp. 242 268
- 4) 橋本達哉・岡本郁男 共著, 固相溶接・ろう付, 溶接全書 9, pp. 95 109
- 5) 日本 溶接學會 界面接合 研究 委員會 編, 最近のろう接・擴散接合技
術, pp. 85 91
- 6) , Al-Si
, (1999),
pp. 6, pp. 27
- 7) 西本和俊, 才田一幸, 妙中 眞, 黒田晋一, I. MAKINO : Al/ステンレ
ス鋼の擴散接合部の組織解析 [Al/ステンレス鋼の擴散接合に関する研
究(第 1 報)], 溶接學會全國大會講演概要 第 64集(1999- 4), pp. 292
293
- 8) , , , : , ,
pp. 283 284

- 9) アルミニウムの組織と性質, 經金屬學會, pp. 477 479
- 10) 黒田晋一, 才田一幸, 西本和俊, A6061とSUS316の 直接接合部の組織と特性 [アルミニウム合金とステンレス鋼の擴散接合に関する研究(第1報)], 溶接學會論文集 第 17卷 第 3 pp. 484 489 (1999)
- 11) I. MAKINO, K.KADA, 黒田晋一, 西本和俊, 才田一幸, 妙中 眞, イサ-ト金属を用いたAl/ステンレス鋼の擴散接合継手特性に及ぼす接合條件の影響, 接學會全國大會講演概要 第 61集(1997- 9)
- 12) 西本和俊, 才田一幸, 妙中 眞, 黒田晋一, I. MAKINO, インサ-ト金属を用いたAl/ステンレス鋼の擴散接合部の組織解析 [Al/ステンレス鋼の擴散接合に関する研究(第 2報)], 接學會全國大會講演概要 第 63集(1998- 10)
- 13) 西本和俊, 才田一幸, 草野満洋, 表面活性化 プリコート インサ-ト金属による擴散接合性の改善, 黒田晋一, [Al/ステンレス鋼の擴散接合に関する研究(第 3報)], 接學會全國大會講演概要 第 64集(1999- 4)
- 14) 最新 接合 加工技術と その 應用, 日本機械學會 編, 日刊工業 新聞社, pp. 74 78
- 15) 特集 先端接合技術と材料複合化への應用, 日本溶接學會誌, 第 59卷 第 2 pp. 17 91 (1990)

- 16) 大橋, 田村, 吉原, 日本溶接學會論文集, vol. 3, No. 1(1985),
pp. 152 158
- 17) 芹野, 益本, 淺田, 本田, 西尾, 迎, 日本溶接學會論文集, vol. 4,
No. 1(1986), pp. 60 66
- 18) 池内, 小谷, 松田, 日本溶接學會論文集, vol. 14, No.1(1996),
pp. 122 128

가

가

金 永植

가

가

, 2 가

